

SOT618-7(DD)

HVQFN40, plastic thermal enhanced very thin quad flat package; no leads, 0.125 dimple wettable flank, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

19 July 2022

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	30-06-2022
Manufacturer package code	98AS01731D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
seated height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	



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2 Package outline

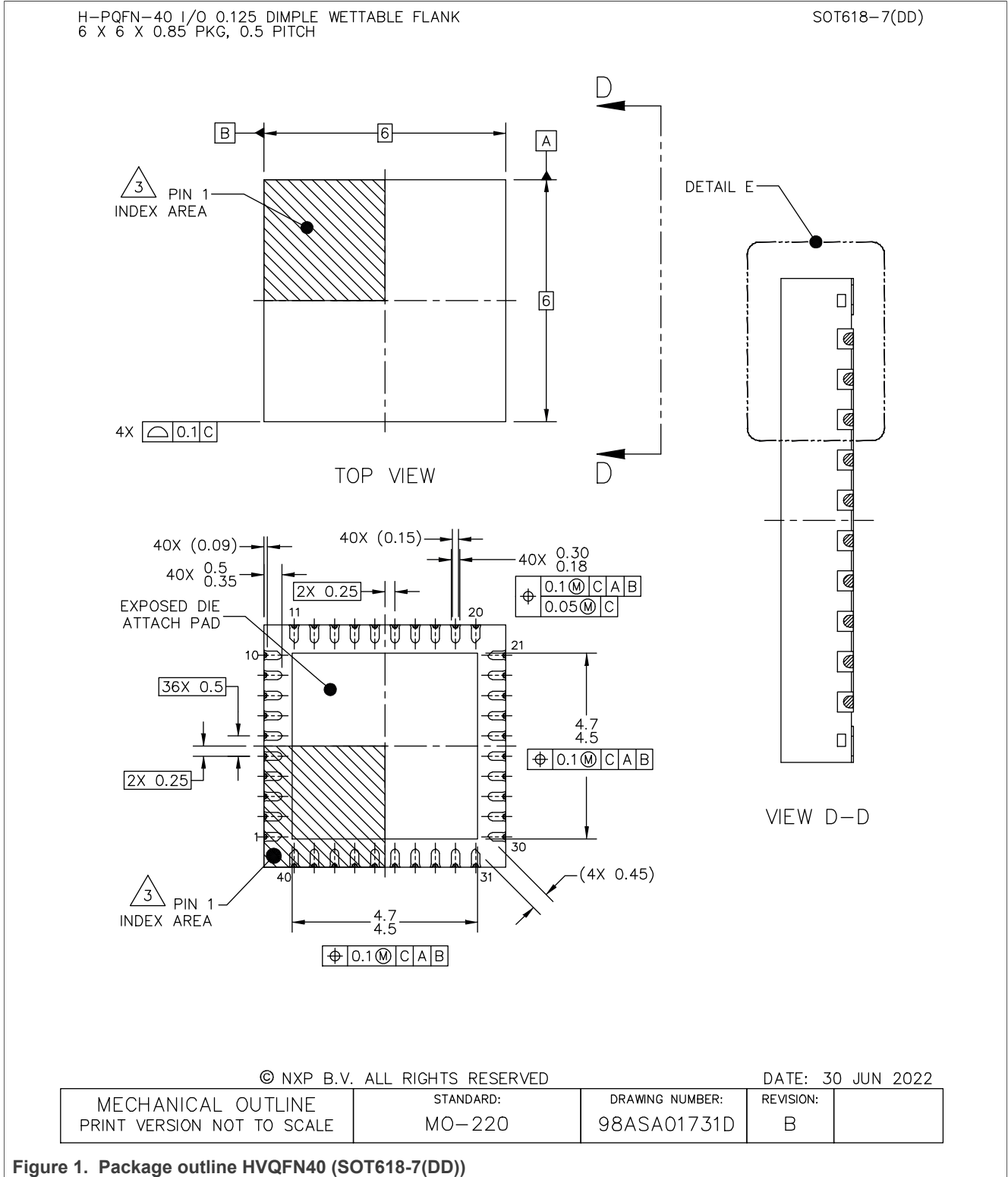
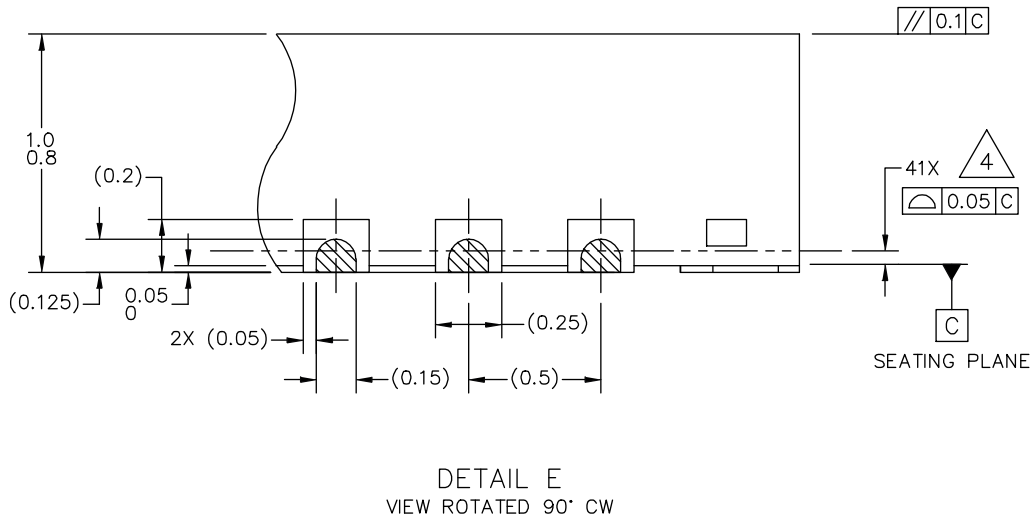


Figure 1. Package outline HVQFN40 (SOT618-7(DD))

HVQFN40, plastic thermal enhanced very thin quad flat package; no leads, 0.125 dimple wettable flank, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-40 I/O 0.125 DIMPLE WETTABLE FLANK
6 X 6 X 0.85 PKG, 0.5 PITCH

SOT618-7(DD)



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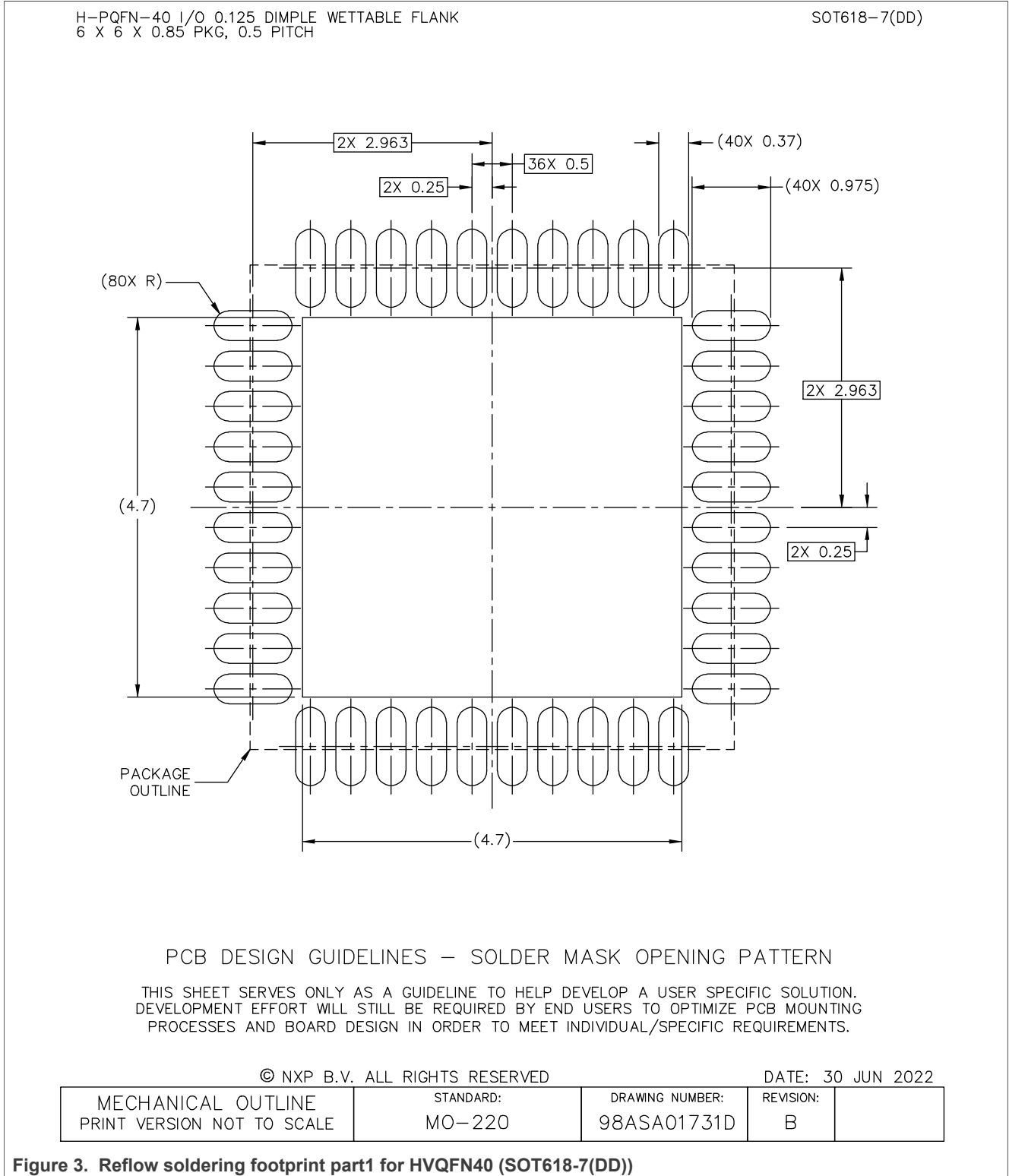
DATE: 30 JUN 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-220	DRAWING NUMBER: 98ASA01731D	REVISION: B	
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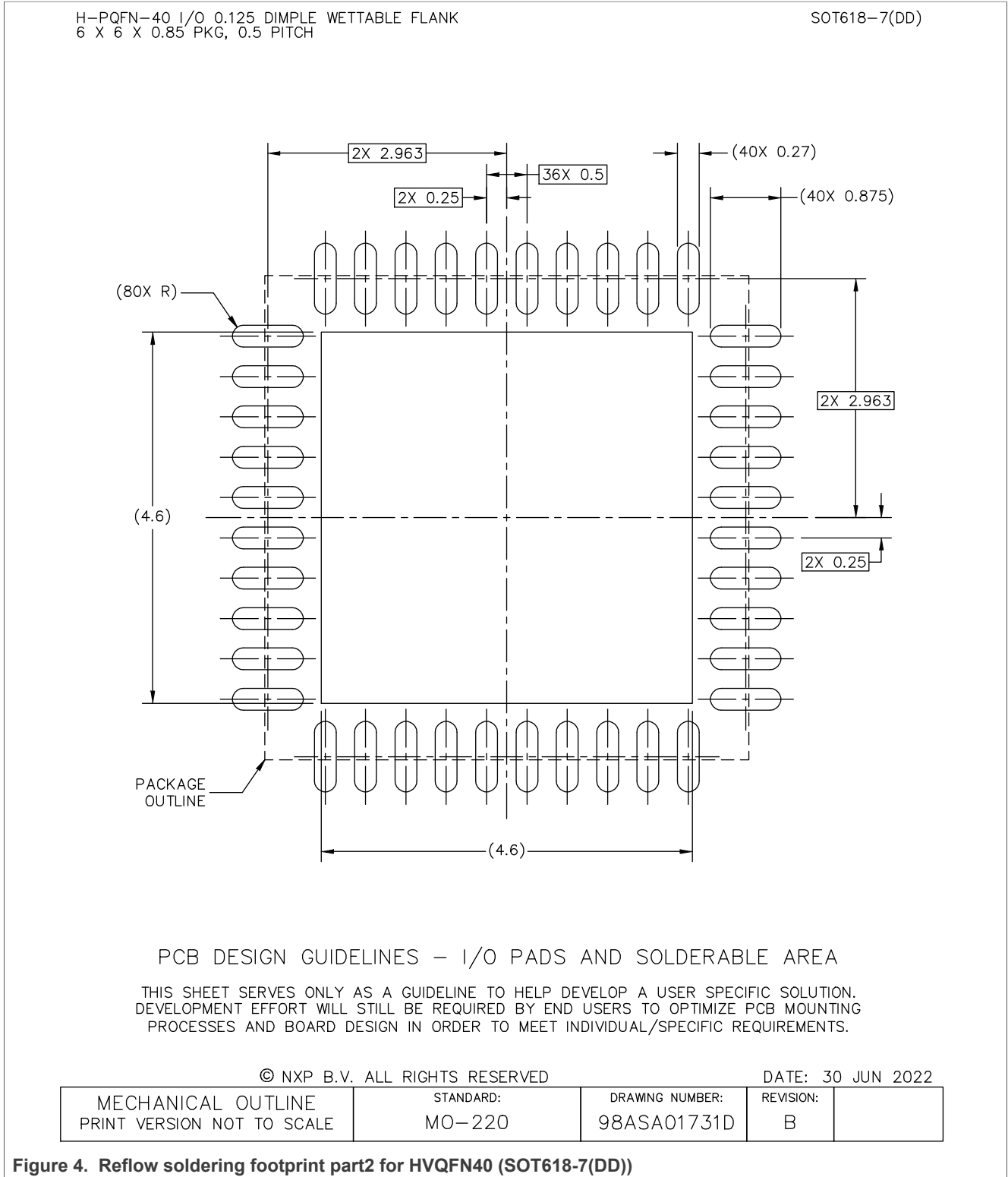
Figure 2. Package outline detail E of HVQFN40 (SOT618-7(DD))

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3 Soldering



HVQFN40, plastic thermal enhanced very thin quad flat package; no leads, 0.125 dimple wettable flank, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body



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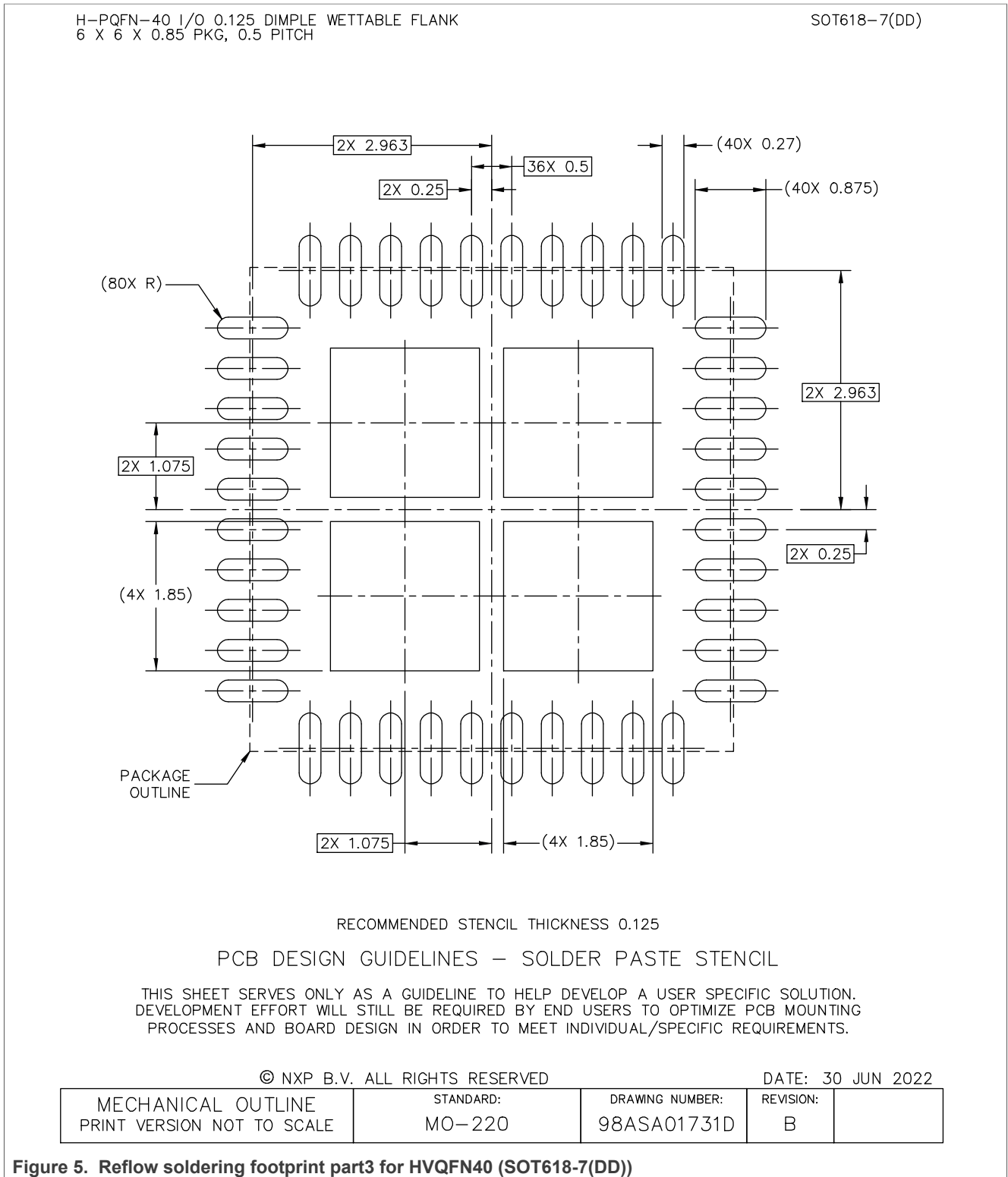


Figure 5. Reflow soldering footprint part3 for HVQFN40 (SOT618-7(DD))

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H-PQFN-40 I/O 0.125 DIMPLE WETTABLE FLANK
6 X 6 X 0.85 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVQFN40 (SOT618-7(DD))

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